
HVD132

Silicon Epitaxial Planar Pin Diode for High Frequency Switching

HITACHI

ADE-208-830A (Z)

Rev. 1
Sep. 2000

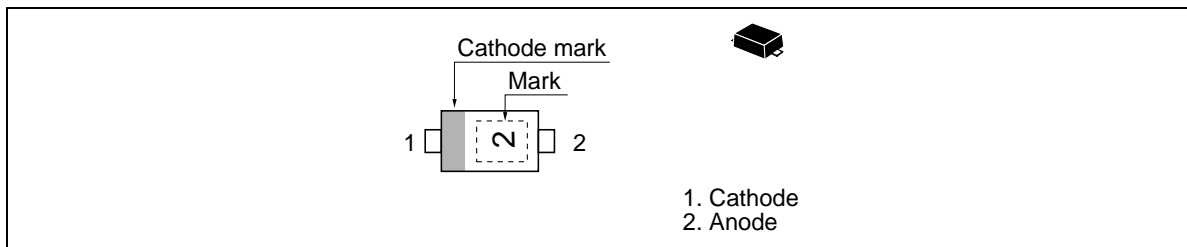
Features

- Low capacitance. ($C = 0.5 \text{ pF max}$)
- Low forward resistance. ($r_f = 2.0 \Omega \text{ max}$)
- Super small Flat Package (SFP) is suitable for surface mount design.

Ordering Information

| Type No. | Laser Mark | Package Code |
|----------|------------|--------------|
| HVD132 | 2 | SFP |

Outline



HVD132

Absolute Maximum Ratings

(Ta = 25°C)

| Item | Symbol | Value | Unit |
|----------------------|----------|-------------|------|
| Peak reverse voltage | V_{RM} | 65 | V |
| Reverse voltage | V_R | 60 | V |
| Forward current | I_F | 100 | mA |
| Power dissipation | Pd | 150 | mW |
| Junction temperature | Tj | 125 | °C |
| Storage temperature | Tstg | -55 to +125 | °C |

Electrical Characteristics

(Ta = 25°C)

| Item | Symbol | Min | Typ | Max | Unit | Test Condition |
|--------------------|--------|-----|-----|-----|------|--|
| Reverse current | I_R | — | — | 0.1 | μA | $V_R = 60\text{ V}$ |
| Forward voltage | V_F | — | — | 1.0 | V | $I_F = 10\text{ mA}$ |
| Capacitance | C | — | — | 0.5 | pF | $V_R = 1\text{ V}, f = 1\text{ MHz}$ |
| Forward resistance | r_f | — | — | 2.0 | Ω | $I_F = 10\text{ mA}, f = 100\text{ MHz}$ |

Note: Please do not use the soldering iron due to avoid high stress to the SFP package.

Main Characteristic

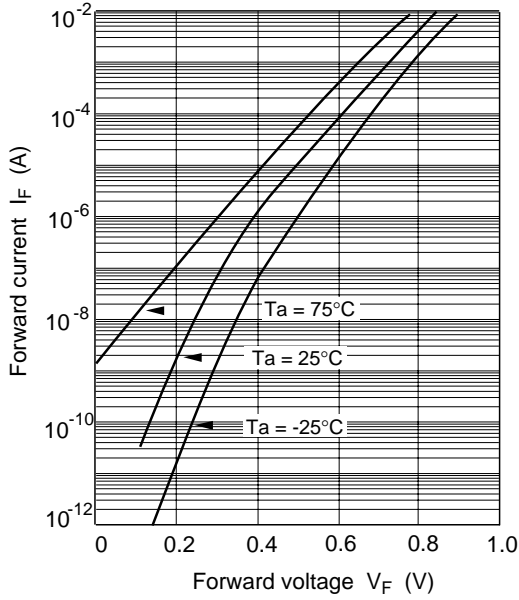


Fig.1 Forward current Vs. Forward voltage

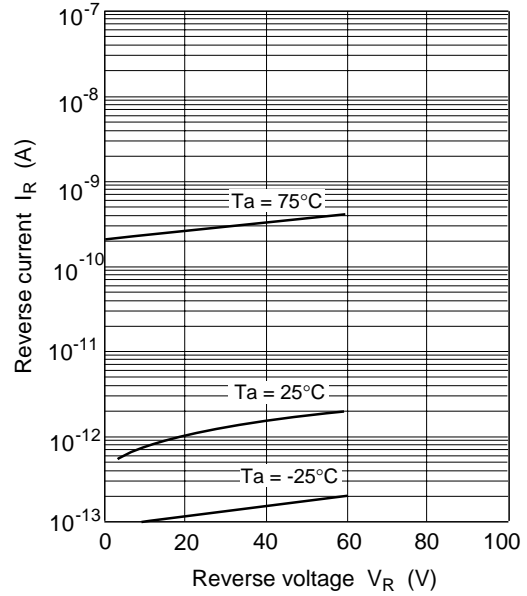


Fig.2 Reverse current Vs. Reverse voltage

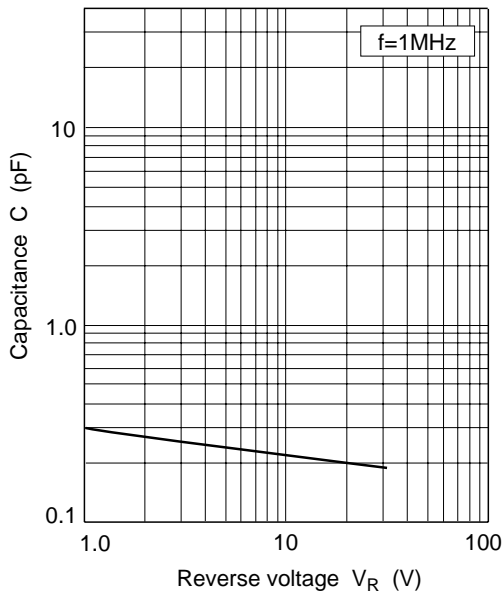


Fig.3 Capacitance Vs. Reverse voltage

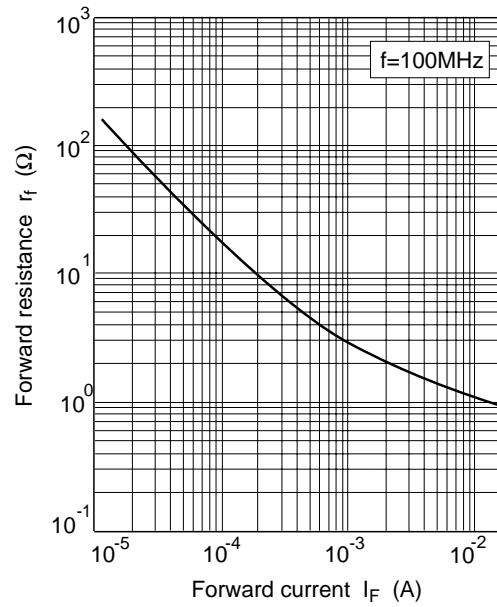
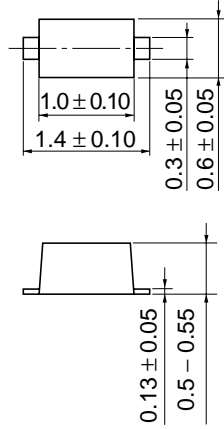


Fig.4 Forward resistance Vs. Forward current

HVD132

Package Dimensions

Unit: mm



| | |
|------------------------|----------|
| Hitachi Code | SFP |
| JEDEC | — |
| EIAJ | — |
| Mass (reference value) | 0.0010 g |

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